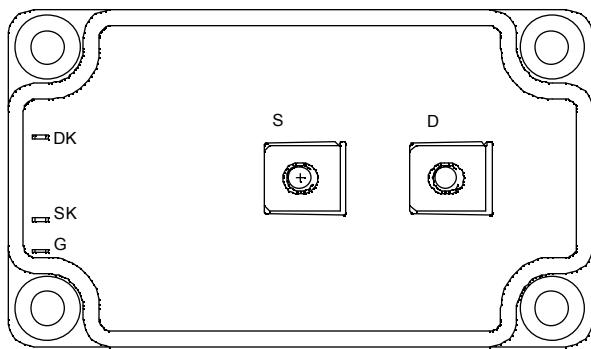
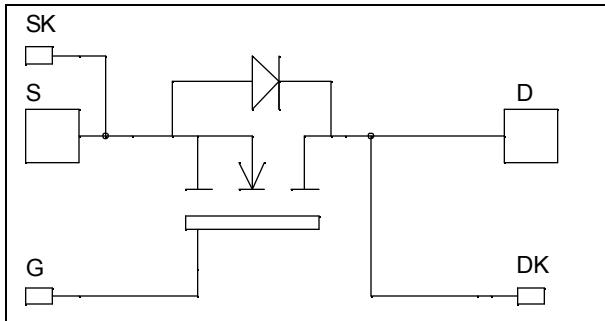


***Single Switch
MOSFET Power Module***

$V_{DSS} = 500V$
 $R_{DSon} = 9 \text{ m}\Omega \text{ typ @ } T_j = 25^\circ\text{C}$
 $I_D = 497A @ T_c = 25^\circ\text{C}$



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS 7[®] FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Fast intrinsic reverse diode
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration
- AlN substrate for improved thermal performance

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage		500	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$	497	A
		$T_c = 80^\circ\text{C}$	371	
I_{DM}	Pulsed Drain current		1988	
V_{GS}	Gate - Source Voltage		± 30	V
R_{DSon}	Drain - Source ON Resistance		10	$\text{m}\Omega$
P_D	Maximum Power Dissipation	$T_c = 25^\circ\text{C}$	5000	W
I_{AR}	Avalanche current (repetitive and non repetitive)		71	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		3000	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}$, $V_{DS} = 500\text{V}$	$T_j = 25^\circ\text{C}$			600	μA
		$V_{GS} = 0\text{V}$, $V_{DS} = 400\text{V}$	$T_j = 125^\circ\text{C}$			3000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}$, $I_D = 248.5\text{A}$			9	10	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 30\text{mA}$		3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30\text{ V}$, $V_{DS} = 0\text{V}$				± 450	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$			63.3		nF
C_{oss}	Output Capacitance				12.4		
C_{rss}	Reverse Transfer Capacitance				0.63		
Q_g	Total gate Charge	$V_{GS} = 10\text{V}$ $V_{Bus} = 250\text{V}$ $I_D = 497\text{A}$			1200		nC
Q_{gs}	Gate – Source Charge				300		
Q_{gd}	Gate – Drain Charge				630		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15\text{V}$ $V_{Bus} = 333\text{V}$ $I_D = 497\text{A}$ $R_G = 0.5\Omega$			21		ns
T_r	Rise Time				42		
$T_{d(off)}$	Turn-off Delay Time				96		
T_f	Fall Time				100		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15\text{V}$, $V_{Bus} = 333\text{V}$ $I_D = 497\text{A}$, $R_G = 0.5\Omega$			6		mJ
E_{off}	Turn-off Switching Energy				6.2		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15\text{V}$, $V_{Bus} = 333\text{V}$ $I_D = 497\text{A}$, $R_G = 0.5\Omega$			9.48		mJ
E_{off}	Turn-off Switching Energy				6.96		

Source - Drain diode ratings and characteristics

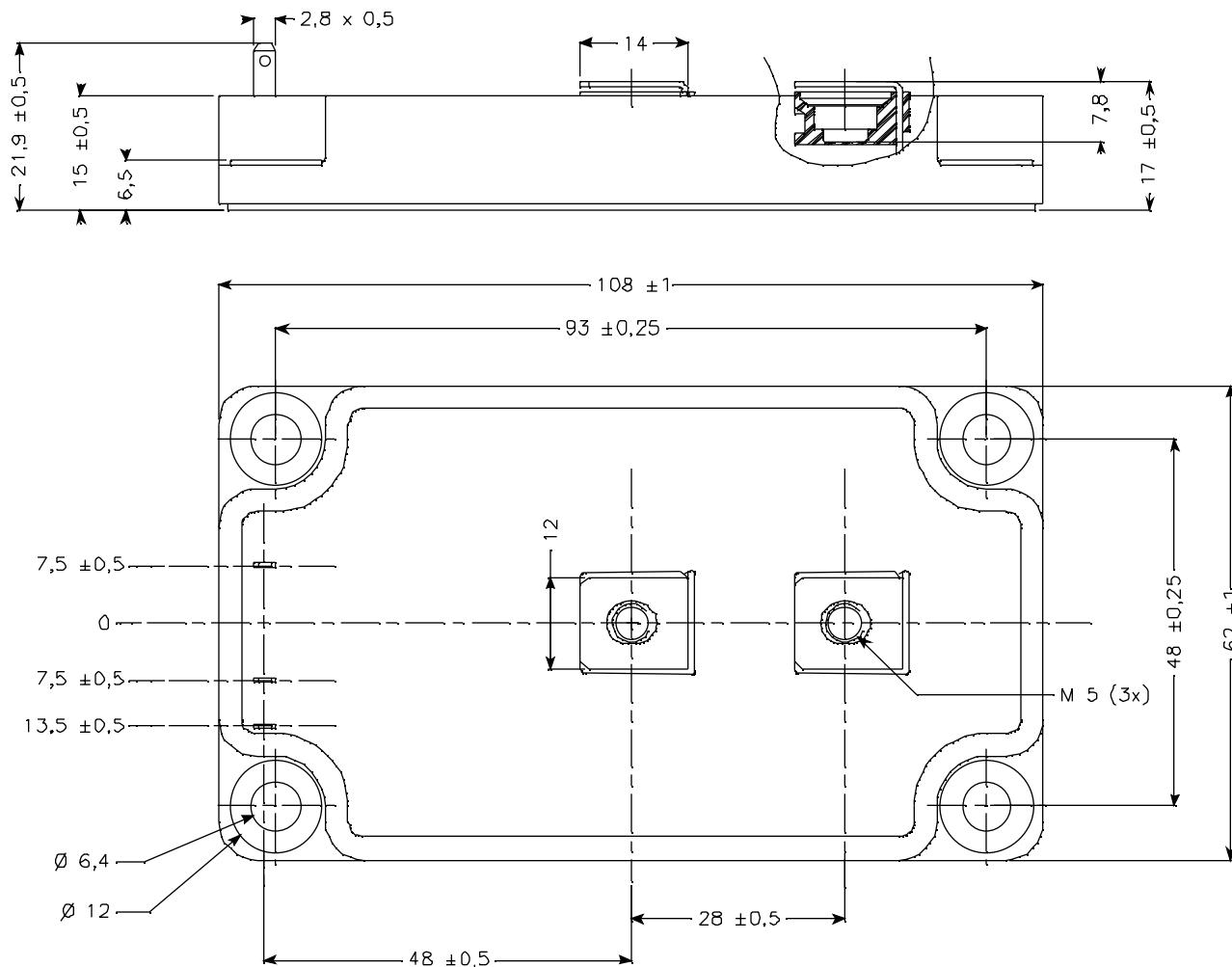
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)		$T_c = 25^\circ\text{C}$			497	A
			$T_c = 80^\circ\text{C}$			371	
V_{SD}	Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_S = - 497\text{A}$				1.3	V
dv/dt	Peak Diode Recovery ①					18	V/ns
t_{rr}	Reverse Recovery Time	$I_S = - 497\text{A}$ $V_R = 333\text{V}$ $dI/dt = 600\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$			300	ns
			$T_j = 125^\circ\text{C}$			600	
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		15.6		μC
			$T_j = 125^\circ\text{C}$		60		

 ① dv/dt numbers reflect the limitations of the circuit rather than the device itself.

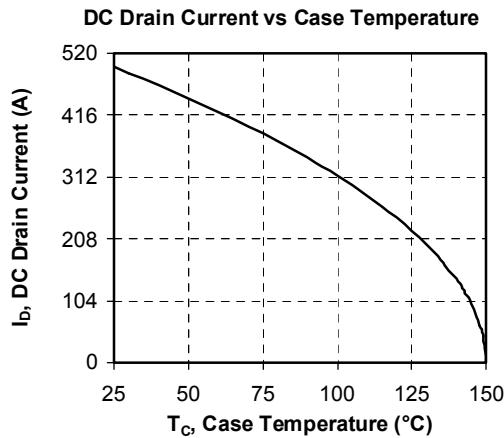
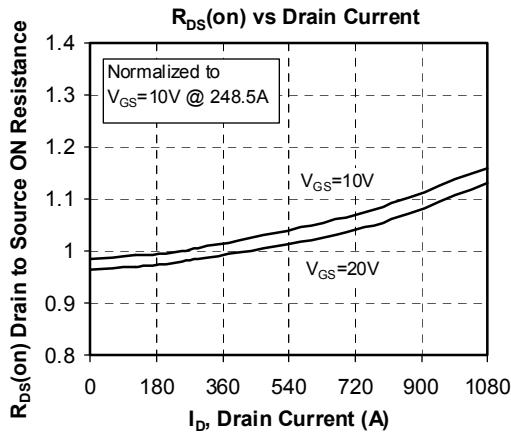
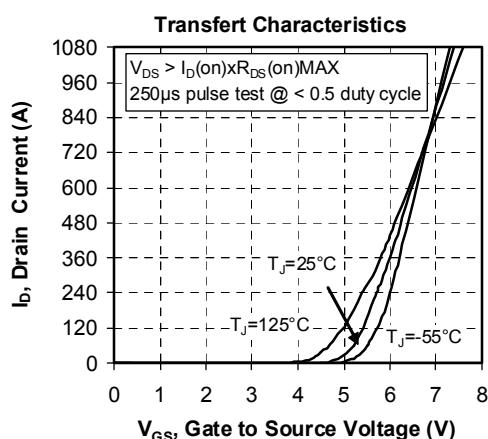
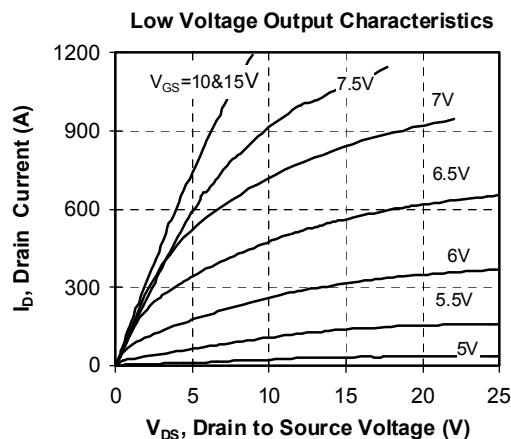
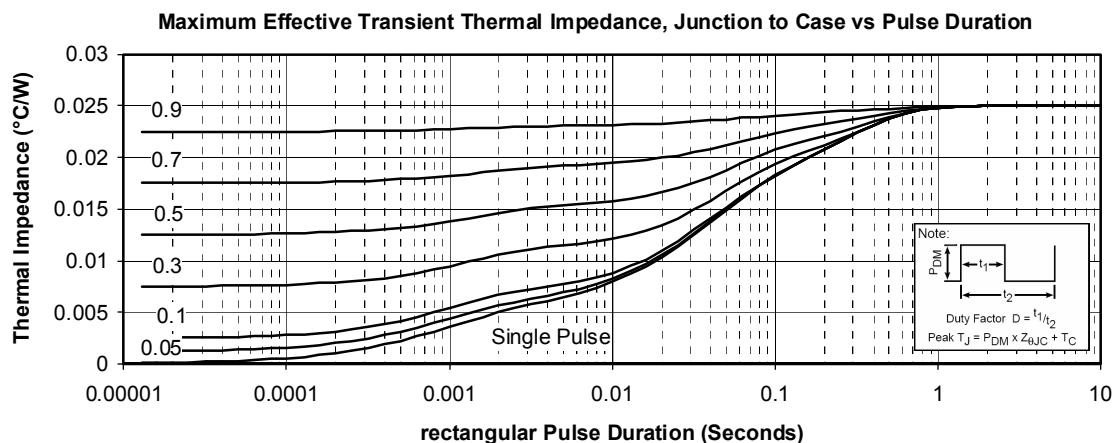
 $I_S \leq - 497\text{A}$ $di/dt \leq 700\text{A}/\mu\text{s}$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ\text{C}$

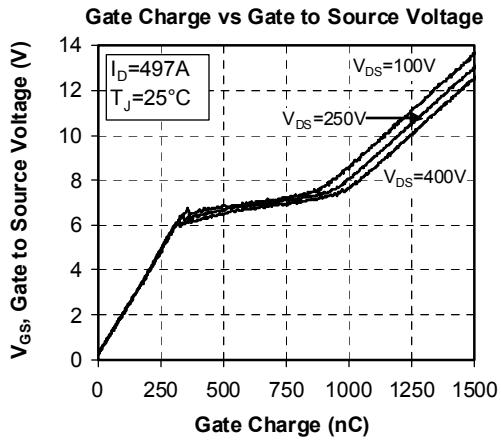
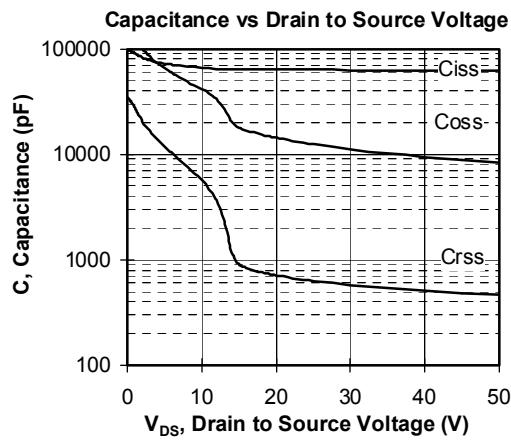
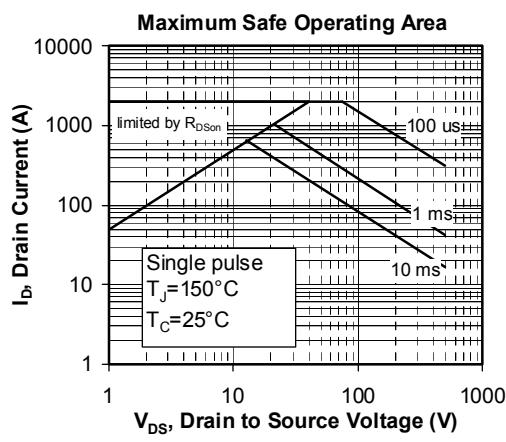
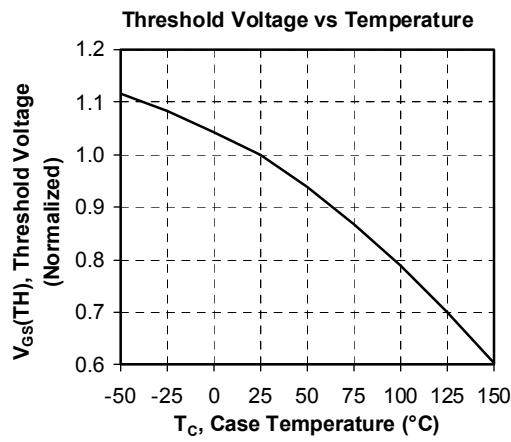
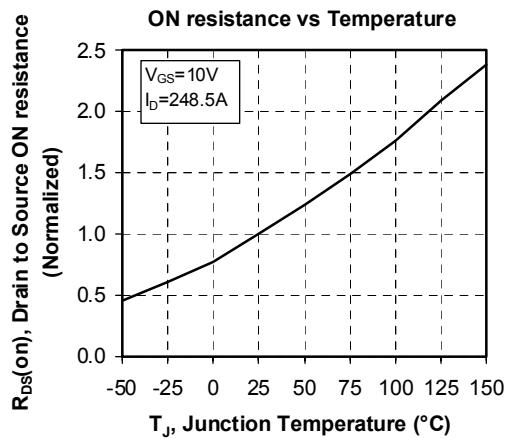
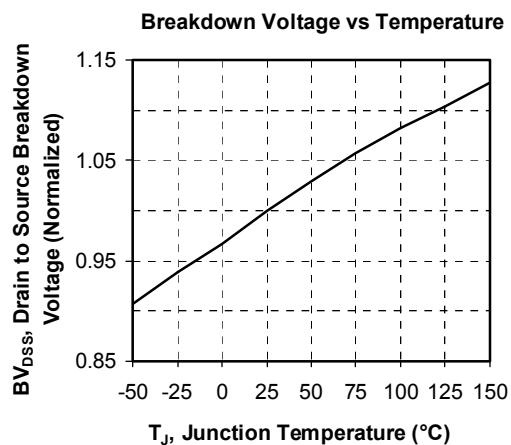
Thermal and package characteristics
Symbol **Characteristic**

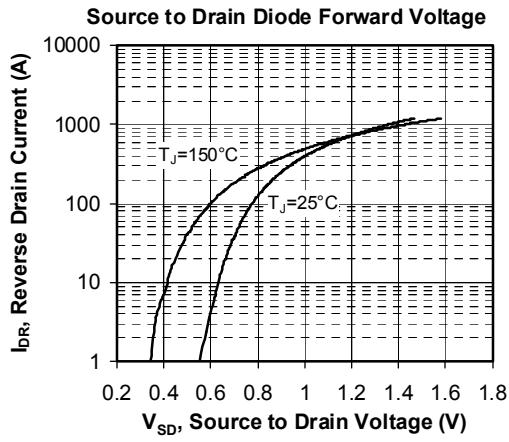
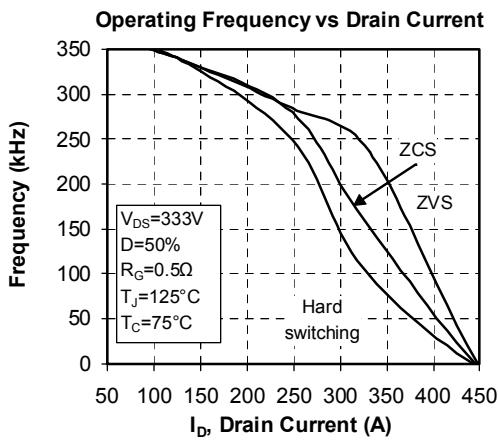
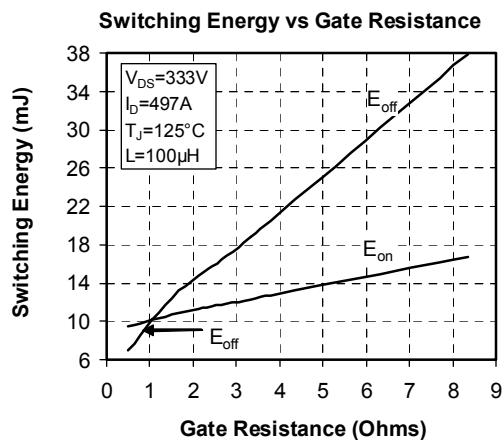
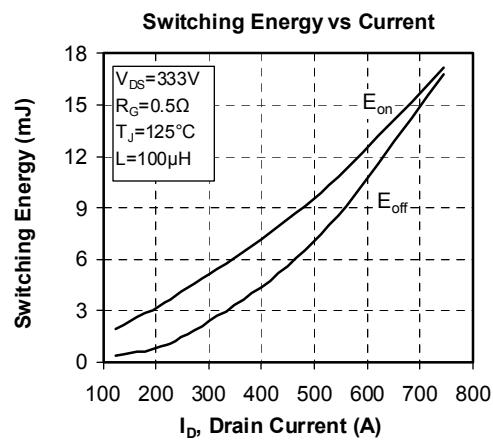
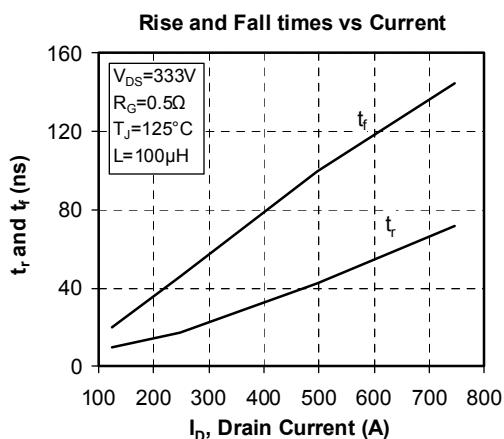
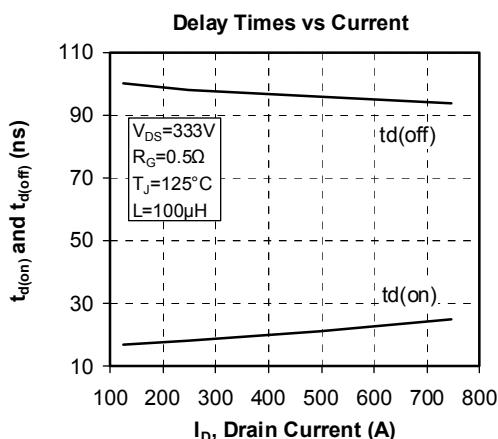
			Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance				0.025	°C/W
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I isol < 1mA, 50/60Hz	2500				V
T _J	Operating junction temperature range	-40		150		
T _{STG}	Storage Temperature Range	-40		125		°C
T _C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To Heatsink For terminals	M6 M5	3 2	5 3.5	N.m
Wt	Package Weight				280	g

SP6 Package outline (dimensions in mm)

 See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve







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